MIL-PRF-38534 CERTIFIED



HIGH SPEED, WIDEBAND OPERATIONAL AMPLIFIER

4707 Dey Road Liverpool, N.Y. 13088

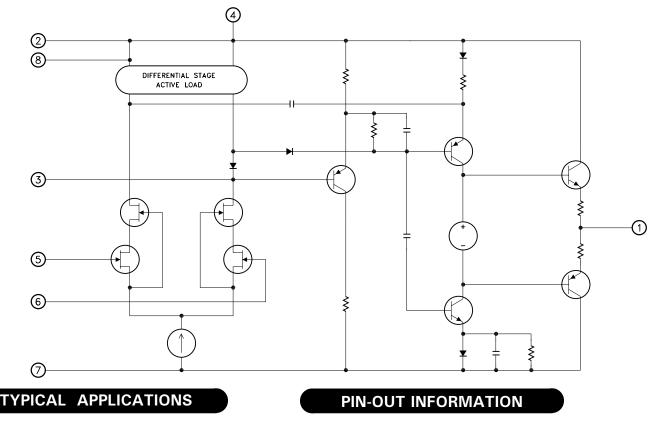
FEATURES:

- Stable at Low Gain
- Fast Slew Rate 1200V/µs Typical
- · Gain Bandwidth Product 1200 MHz Typical
- · Low Quiescent Current \pm 14.0 mA Typical
- Low Offset 2 mV Maximum
- Drop In Replacement for OPA 3554 and TP 3554
- High Output Current ±100mA Minimum
- · Contact MSK for MIL-PRF-38534 Qualification Status

DESCRIPTION:

The MSK 3554 is a pin compatible, low gain stable, drop-in replacement for the OPA 3554 and TP 3554. The MSK 3554 does not exhibit high frequency output oscillations like other versions of the 3554 when operated at closed loop gains of less than 55 V/V. The extremely low input bias current and input offset voltage ratings coupled with a high slew rate and wide bandwidth make the MSK 3554 an excellent choice for fast D/A converters, buffers, pulse amplifiers and other high speed op-amp applications. The MSK 3554 is packaged in an 8-pin TO-3 using thick film hybrid technology to obtain high reliability and compact size.

EQUIVALENT SCHEMATIC



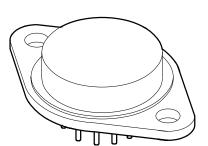
- Fast D/A Converters
- Pulse Amplifiers
- Video Instrumentation
- Fast Buffer/Follower
- Video Frequency Filters

- 1 Output
- 2 Positive Power Supply
- 3 Compensation
- 4 Balance 1

1

- 8 Balance 2
- 7 Negative Power Supply
- 6 Non-Inverting Input
- 5 Inverting Input





3554

(315) 701-6751

ABSOLUTE MAXIMUM RATINGS

±Vсс	Supply Voltage
Іоит	Peak Output Current ± 150mA
Vin	Differential Input Voltage ±25V
Tc	Case Operating Temperature
	MSK 3554B
	MSK 3554 \ldots \ldots $.40^{\circ}$ C to $+85^{\circ}$ C

(1)

Storage Temperature Range -6	65°C to +150°C
Lead Temperature Range	300°C
(10 Seconds)	
Power Dissipation	See Curve
Junction Temperature	175°C
	Lead Temperature Range (10 Seconds) Power Dissipation

ELECTRICAL SPECIFICATIONS

Parameter	Test Conditions	Group A	Group A MSK 3554B/E		MSK 3554				
Parameter Test Conditions		Subgroup	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
STATIC									
Supply Voltage Range ③		-	±12	±15	±18	±12	±15	±18	V
Quiescent Current	VIN=OV	1	-	±14	±20	-	±14	±20	mA
	Av = -1v/v	2,3	-	-	± 30	-	-	-	mA
Thermal Resistance ③	Junction to Case Output Devices	-	-	37	-	-	37	-	°C/W
INPUT									
Input Offset Voltage	Bal.Pins = N/C $V_{IN} = 0V A_V = -10V/V$	1	-	±0.5	±2.0	-	±0.5	±3.0	mV
Input Offset Voltage Drift	VIN=OV	2,3	-	±20	±50	-	±20	-	µV/°C
Input Offset Adjust 3	$R_{POT} = 20K\Omega To + Vcc Av = -1v/v$	1,2,3	Adjust to Zero Adjust to Zero		ero	mV			
Input Bias Current 🔞	Vcm=0V Either Input	1	-	±10	±50	-	±20	±100	pА
		2,3	-	±10	±50	-	-	-	nA
Input Offset Current	Vcm=0V	1	-	±2.0	±25	-	±2.0	±30	pА
		2,3	-	±2.0	± 30	-	-	-	nA
Input Impedance ③	F = DC Differential	-	-	10 ¹¹	-	-	10 ¹¹	-	Ω
Power Supply Rejection Ratio	(3) Δ Vcc = 10V	-	80	110	-	80	110	-	dB
Input Noise Density ③	F = 1KHz	-	-	15	-	-	15	-	nV√Hz
Input Noise Voltage ③	F=10Hz To 1MHz	-	-	10.0	-	-	10.0	-	μVrms
OUTPUT									
Output Voltage Swing	$RL = 100\Omega$	4	±10.5	±12	-	±10	±12	-	V
Output Current	TJ<150°C	4	±100	±120	-	±100	±120	-	mA
Settling Time 23	0.1% 10V step	4	-	120	150	-	120	150	nS
Power Bandwidth ③	$R_L = 100\Omega$ Vo = ± 10V Cc = 0	4	16	19	-	15	19	-	MHz
Bandwidth (Small Signal) ③	Cc = 0	4	70	90	-	70	90	-	MHz
TRANSFER CHARACTERISTICS									
Slew Rate	$V_{OUT} = \pm 10V \text{ RL} = 100\Omega \text{ Cc} = 0$	4	800	1200	-	750	1200	-	V/µS
Open Loop Voltage Gain ③ C	$c = 0 RL = 100\Omega F = 1 KHz Vout = \pm 10V$	4	90	96	-	88	96	-	dB

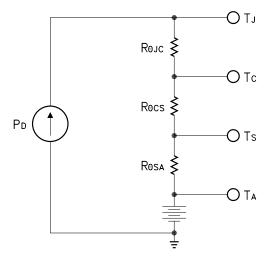
NOTES:

- (1) Unless otherwise specified $\pm VCC = \pm 15VDC$
- 2 AV = -1, measured in false summing junction circuit.
 3 Devices shall be capable of meeting the parameter, but need not be tested. Typical parameters are for reference only.
 4 Industrial grade and "E" suffix devices shall be tested to subgroups 1 and 4 unless otherwise specified.
- 5 Military grade devices ('B' suffix) shall be 100% tested to subgroups 1,2,3 and 4.
- 6 Subgroup 5 and 6 testing available upon request. $TA = TC = +25 \circ C$
- O Subgroup 1,4
- 8 Subgroup 2,5 TA = TC = +125 °C
- 9 Subgroup 3,6 $TA = TC = -55 \circ C$
- 1 Measurement taken .5 second after application of power using automatic test equipment.
- (1) Continuous operation at or above absolute maximum ratings may adversely effect the device performance and/or life cycle.

HEAT SINKING

Refer to the following thermal model and governing equations to determine appropriate heat sinking for your application.

Thermal Model:



Governing Equation:

 $T_J = P_D x (R_{\theta JC} + R_{\theta CS} + R_{\theta SA}) + T_A$

Where

- $T_J = Junction Temperature$
- PD = Total Power Dissipation
- $R_{\theta JC}$ = Junction to Case Thermal Resistance
- $R_{\theta}CS = Case to Heat Sink Thermal Resistance$
- $R_{\theta SA}$ = Heat Sink to Ambient Thermal Resistance
- Tc = Case Temperature
- TA = Ambient Temperature
- Ts = Sink Temperature

Example:

This example demonstrates a worst case analysis for the opamp output stage. This occurs when the output voltage is 1/2 the power supply voltage. Under this condition, maximum power transfer occurs and the output is under maximum stress.

Conditions:

 $\label{eq:Vcc} \begin{array}{ll} Vcc = \pm 16 VDC \\ Vo = \pm 8 Vp \mbox{ Sine Wave, Freq.} = 1 KHZ \\ R_L = 100 \Omega \end{array}$

For a worst case analysis we will treat the +8Vp sine wave as an 8 VDC output voltage.

- 1.) Find Driver Power Dissipation
 - PD = (Vcc-Vo) (Vo/RL)
 - = (16V-8V) (8V/100 Ω)

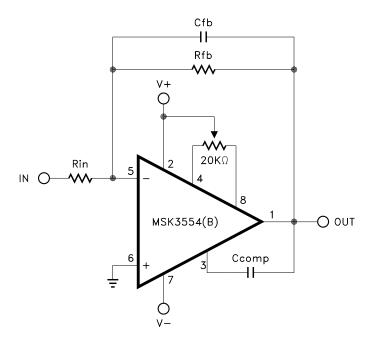
- 2.) For conservative design, set $T_J = +125 \,^{\circ}C$
- 3.) For this example, worst case $T_A = +90^{\circ}C$
- 4.) R_{θ JC} = 37°C/W from MSK 3554B Data Sheet
- 5.) $R_{\theta}CS = 0.15^{\circ}C/W$ for most thermal greases
- 6.) Rearrange governing equation to solve for R0SA

$$\begin{array}{l} \mathsf{R}_{\theta \mathsf{SA}} = ((\mathsf{T}_\mathsf{J} - \mathsf{T}_\mathsf{A})/\mathsf{P}_\mathsf{D}) - (\mathsf{R}_{\theta}\mathsf{J}_\mathsf{C}) - (\mathsf{R}_{\theta}\mathsf{C}_\mathsf{S}) \\ = ((125^\circ\mathsf{C} - 90^\circ\mathsf{C}) \ / \ .64\mathsf{W}) - 37^\circ\mathsf{C}/\mathsf{W} - .15^\circ\mathsf{C}/\mathsf{W} \\ = 54.7 - 37.15 \\ = 17.54^\circ\mathsf{C}/\mathsf{W} \end{array}$$

The heat sink in this example must have a thermal resistance of no more than 17.54 °C/W to maintain a junction temperature of no more than +125 °C.

OFFSET NULL

Typically, the MSK 3554(B) has an input offset voltage of less than $\pm 0.5 mV$. If it is desirable to adjust the offset closer to "zero", or to a value other than "zero", the circuit below is recommended. Rp should be a ten-turn 20K Ω potentiometer. Typical offset adjust is $\pm 20 mV.$

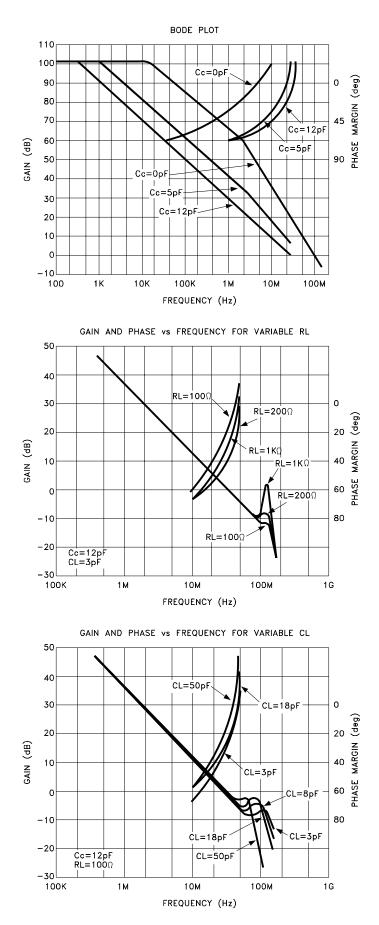


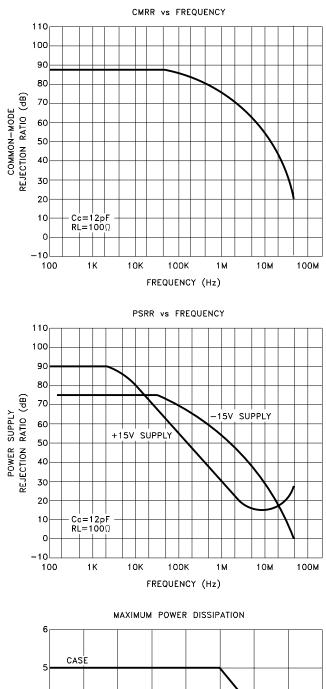
COMPENSATION

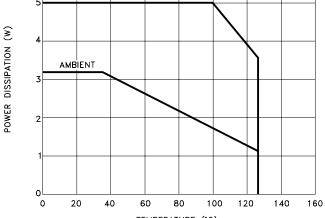
The compensation capacitor is connected between pins 1 and 3 and is used to optimize bandwidth and slew rate while maintaining circuit stability. The effect of compensation capacitance can be seen in the Bode Plot under the Typical Performance Curves. As closed loop gain increases, compensation capacitance can decrease and higher slew rates and wider bandwidths will be realized. See the component selection table for recommended values of input and feedback resistance as well as feedback capacitance and compensation capacitance.

COMPONENT SELECTION TABLE				
GAIN	Rin	Rfb	Cfb	Ccomp
-1	5.6KΩ	5.6KΩ	2.0pF	10pF
-10	560Ω	5.6KΩ	1.2pF	10pF
-100	100Ω	10KΩ	0.0pF	0.0pF
follower	0Ω	0Ω	OpF	12pF

TYPICAL PERFORMANCE CURVES

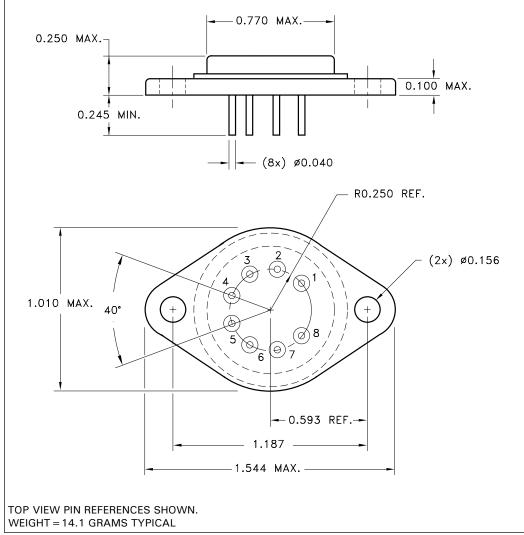






TEMPERATURE (*C)

MECHANICAL SPECIFICATIONS



ALL DIMENSIONS ARE ±0.010 INCHES UNLESS OTHERWISE LABELED

ORDERING INFORMATION

Part Number	Screening Level
MSK3554	Industrial
MSK3554E	Extended Reliability
MSK3554B	Mil-PRF-38534 Class H

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